

SPY0029A

Linear Regulator

Preliminary

APR. 15, 2005

Version 0.6

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LINEAR REGULATOR

1. GENERAL DESCRIPTION

The SPY0029A is a voltage regulator IC with ultra-low quiescent current and low voltage detection by CMOS process. It operates to +7.0V input range and delivers up to 100mA.

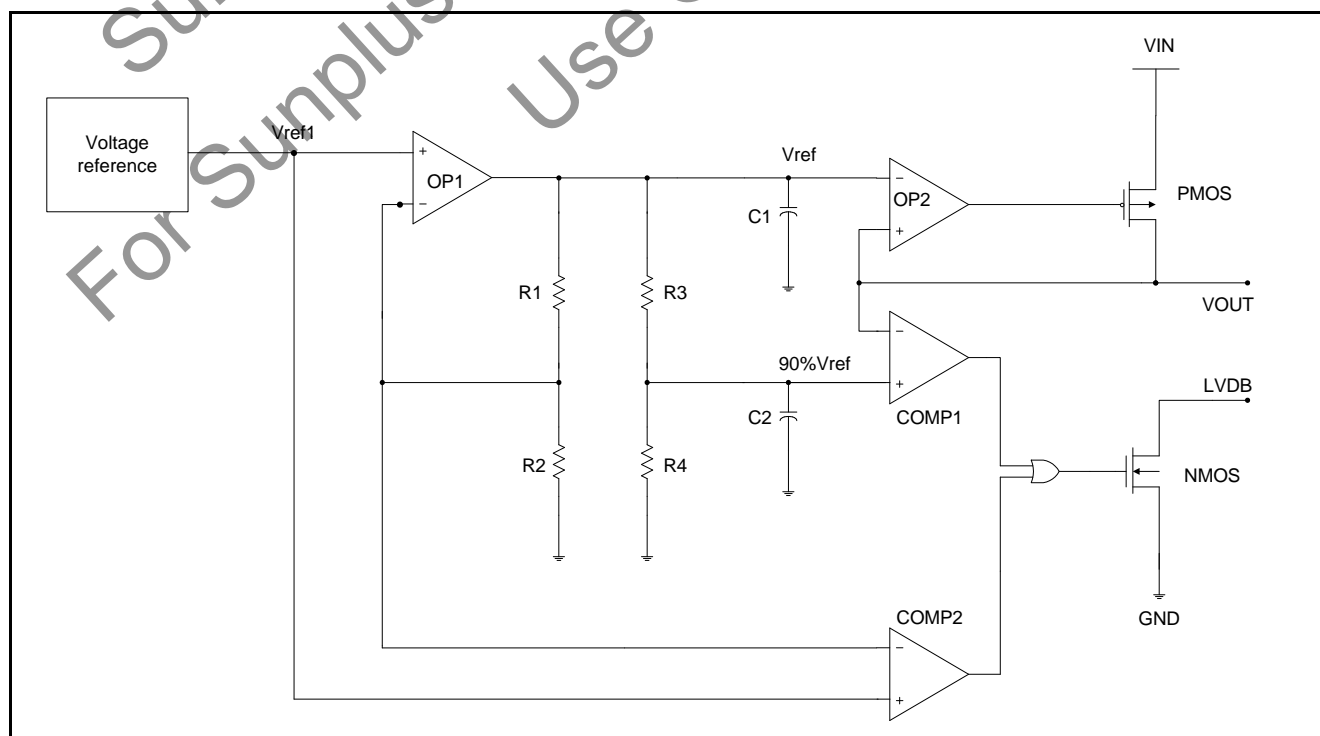
2. APPLICATION

- Battery-powered equipment
- Hand-held communication equipment
- Audio/Video system
- Toys

3. FEATURES

- Low Quiescent Current (Typ. 3 μ A @ $V_{OUT} = 3.3V$, $V_{IN} = 5.0V$)
- High Current Driving Capability (Typ. 100mA @ $V_{OUT} = 3.3V$, $V_{IN} = 5.0V$)
- Small Dropout Voltage (Typ. 40mV @ $V_{OUT} = 3.3V$, $I_{OUT} = 1.0mA$)
- Low Temperature-Drift Coefficient of Output Voltage (Typ. $\pm 50ppm/^{\circ}C$)
- Excellent Line Regulation (Typ. 0.15%/V)
- Bonding Options Output Voltage (2.55V, 2.7V, 3.0V, 3.3V)
- High Accuracy Output Voltage ($\pm 10\%$)
- Low Voltage Detection.
(A. Overload detection, B. Low battery detection)
- 3 pin Types of Package or Dice Form

4. BLOCK DIAGRAM



5. SIGNAL DESCRIPTIONS

5.1. 4 PIN only for chip on board (COB)

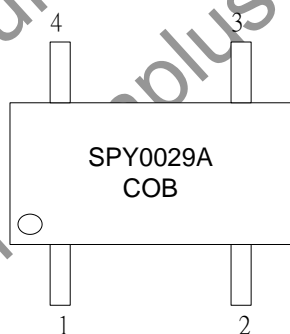
| Mnemonic | PIN No. | Type | Description |
|----------|---------|------|-------------------------------------|
| LVDB | 1 | O | Low voltage detection, Low activity |
| GND | 2 | G | Chip Ground |
| VOUT | 3 | O | Output Regulated Voltage. |
| VIN | 4 | I | Input Voltage. |

5.2. 3 PIN (SOT-89)

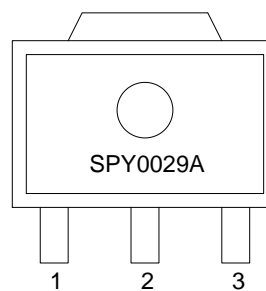
| Mnemonic | PIN No. | Type | Description |
|----------|---------|------|---------------------------|
| GND | 1 | G | Chip Ground |
| VIN | 2 | I | Input Voltage. |
| VOUT | 3 | O | Output Regulated Voltage. |

5.3. PIN Configuration

Customize COB-4pin



SOT-89



6. ELECTRICAL SPECIFICATIONS

6.1. Absolute Maximum Ratings

| Characteristic | Symbol | Rating | Unit |
|-----------------------|------------|---------------------------|------|
| Input Voltage | V_{IN} | +7.0V | V |
| Output Voltage | V_{OUT} | -0.3 ~ ($V_{IN} + 0.3$) | V |
| Operating Temperature | T_{OPT} | 0 - 70 | °C |
| Storage Temperature | T_{STG} | -40 - 125 | °C |
| Power Consumption (#) | P_{WATT} | 500 | mW |

Note1: Stresses beyond those given in the "Absolute Maximum Ratings" table may cause operational errors or damage to the device. For normal operational conditions see Electrical Characteristic

Note2: (#) applied to SOT-89 package

Note3: For bonding-wire current density & package power dissipation issues, we do not suggest that the power consumption exceed "Absolute Maximum Ratings"; it may cause device damage or affect device reliability

6.2. DC Characteristic

($V_{OUT}(\text{target}) = 3.3V / 3.0V / 2.7V / 2.55V$, Typical values are at $T_{OPT} = 25^\circ\text{C}$)

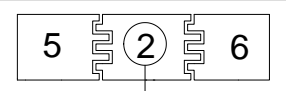
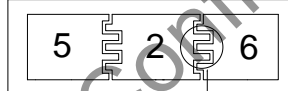
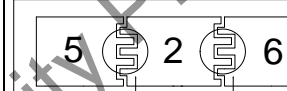
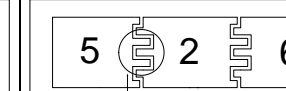
| Item | Test Conditions | Symbol | Min. | Typ. | Max. | Unit |
|-------------------------------------------|----------------------------------------------------------------------------------------------------------|-------------------------------------------------------------------|-------|----------|------|---------|
| Output Voltage Accuracy | $V_{IN} = 5.0V$, $10\mu A \leq I_{OUT} \leq 10mA$, $V_{OUT} = 3.3V$ | $\frac{V_{out} - V_{out}(\text{target})}{V_{out}(\text{target})}$ | -10.0 | - | 10.0 | % |
| Output Current | $V_{IN} = 5.0V$, $V_{OUT} = 3.3V$ | I_{OUT} | 50 | 100 | - | mA |
| Load Regulation | $V_{IN} = 5.0V$, $1mA \leq I_{OUT} \leq 50mA$, $V_{OUT} = 3.3V$ | ΔV_{OUT} | - | 40 | 60 | mV |
| Dropout Voltage | $I_{OUT} = 1mA$, $V_{in} = V_{OUT}(\text{normal})$, $V_{DIF} = V_{IN} - V_{OUT}$, $V_{OUT} = 3.3V$ | V_{DIF} | - | 40 | 60 | mV |
| Quiescent Current | $V_{IN} = 5.0V$, $V_{OUT} = 3.3V$ | I_{SS} | - | 3.0 | 6.0 | μA |
| Line Regulation | $I_{OUT} = 1mA$, $V_{OUT} + 0.5V \leq V_{IN} \leq 7.0V$, $V_{OUT} = 3.3V$ | $\frac{\Delta V_{out}}{\Delta V_{in} \times V_{out}}$ | - | 0.15 | - | %/V |
| Input Voltage | $V_{OUT} = 3.3V$ | V_{IN} | - | - | 7.0 | V |
| Temperature Coefficient | $I_{OUT} = 10mA$, $0^\circ\text{C} \leq T_{OPT} \leq 70^\circ\text{C}$, $V_{OUT} = 3.3V$ | $\frac{\Delta V_{out}}{\Delta T}$ | - | ± 50 | - | ppm/°C |
| Low Voltage Detection Threshold | (A) $1 - \frac{V_{out}}{V_{out}(\text{Normal})}$, $V_{OUT} = 3.3V$ | V_{DET} | 5.0 | 10 | 15 | % |
| | (B) $\Delta V = V_{OUT}(\text{Normal}) - V_{IN}$, $V_{OUT} = 3.3V$ | ΔV | - | ± 60 | - | mV |
| LVDB Output Voltage Low (Open Nmos Drain) | $I_{SINK} = 1mA$, $V_{OUT} = 3.3V$ | VO_L | - | - | 0.4 | V |

Note1: $V_{OUT}(\text{normal})$ @ $V_{IN} = 5.0V$, $I_{OUT} = 1mA$, $V_{out} = 3.3V$, $T_{OPT} = 25^\circ\text{C}$

Note2: $P_{watt} = (V_{IN} - V_{OUT}) \times I_{OUT}$; SOT-89 package maximum power dissipation is 500mW for SPY0029

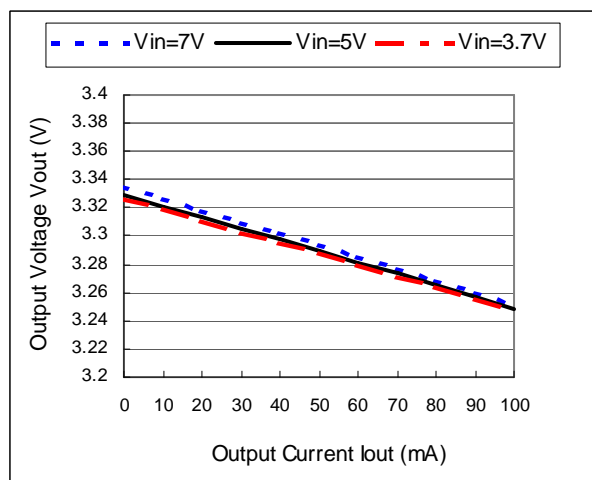
6.3. Bonding Option (several output voltage)

| Option | Output voltage | Power source bonding PAD no. |
|--------|----------------|------------------------------|
| 1 | 3.3V | 2 (note1) |
| 2 | 3.0V | 2 & 6 (note 2) |
| 3 | 2.7V | 2 & 5 & 6 (note 3) |
| 4 | 2.55V | 2 & 5 (note 4) |

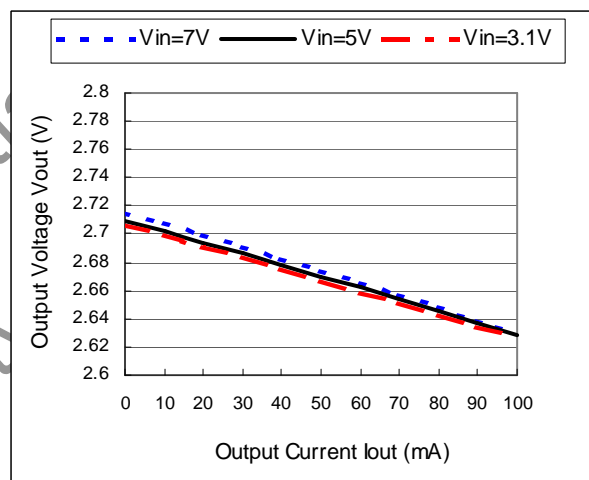
| Note 1 | Note 2 | Note 3 | Note 4 |
|--------------------------------------------------------------------------------------------------------|--------------------------------------------------------------------------------------------------------|---------------------------------------------------------------------------------------------------------|----------------------------------------------------------------------------------------------------------|
|  <p>Bonding Point</p> |  <p>Bonding Point</p> |  <p>Bonding Point</p> |  <p>Bonding Point</p> |

6.4. Typical Operating Characteristics

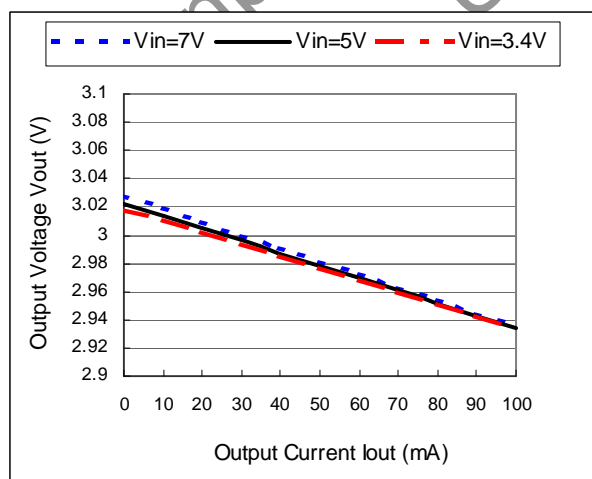
6.4.1. Output voltage vs. output current ($V_{out} = 3.3V$)



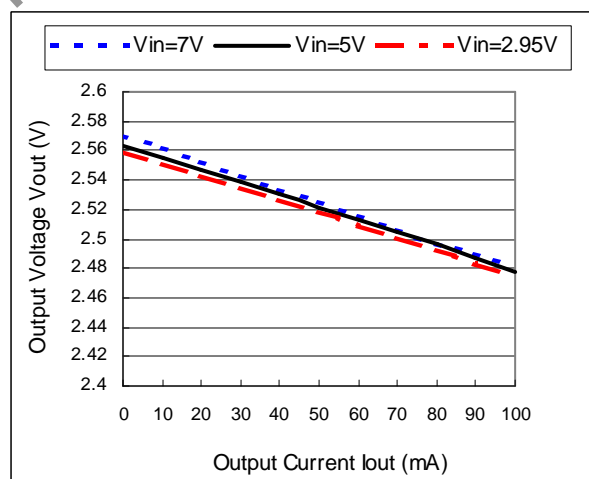
6.4.3. Output voltage vs. output current ($V_{out} = 2.7V$)

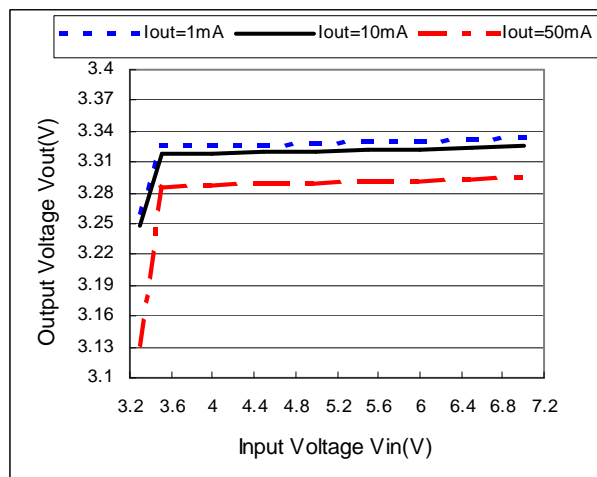
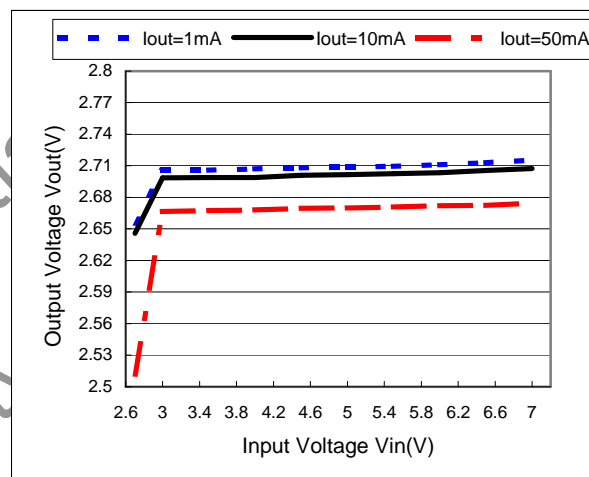
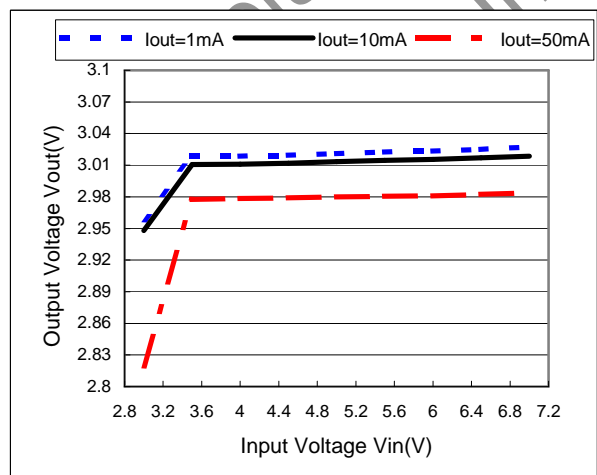
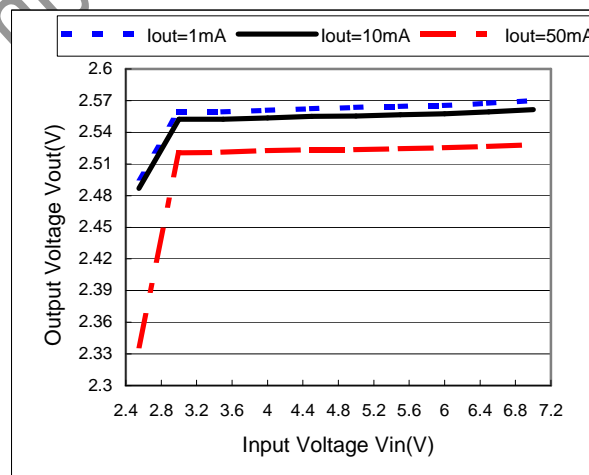


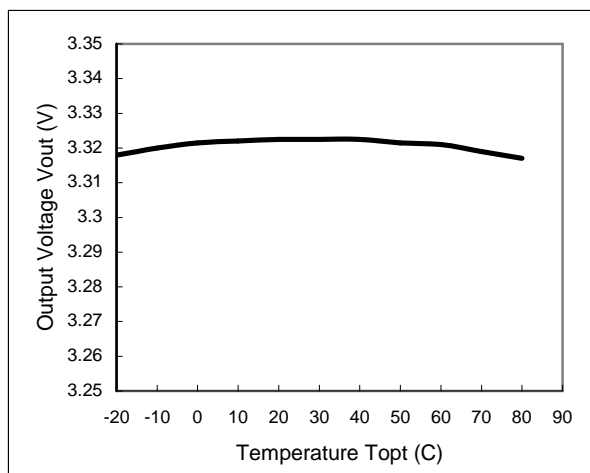
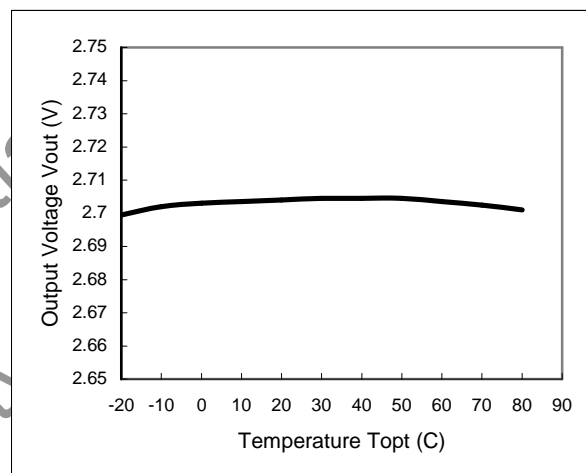
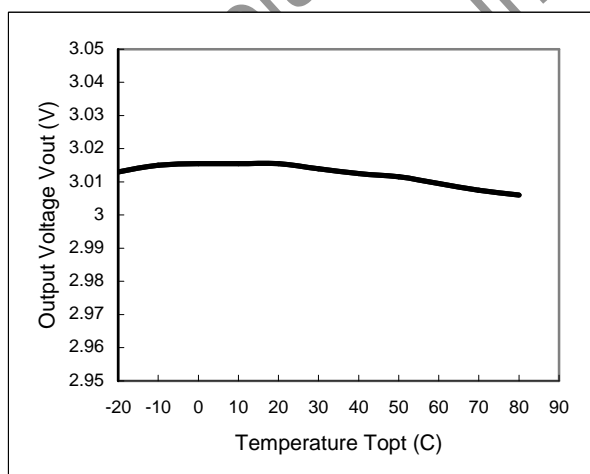
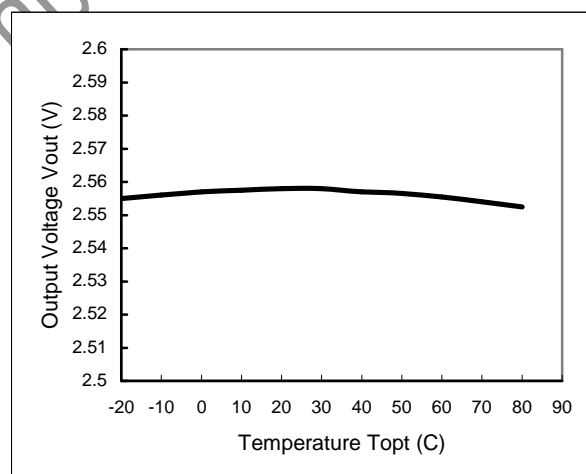
6.4.2. Output voltage vs. output current ($V_{out} = 3.0V$)



6.4.4. Output voltage vs. output current ($V_{out} = 2.55V$)

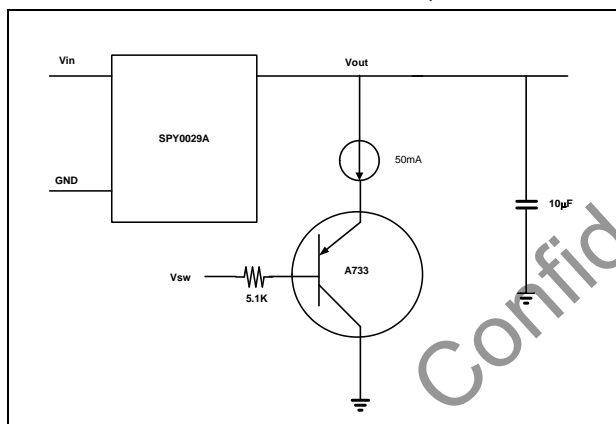


6.4.5. Output voltage vs. input voltage ($V_{out} = 3.3V$)

6.4.7. Output voltage vs. input voltage ($V_{out} = 2.7V$)

6.4.6. Output voltage vs. input voltage ($V_{out} = 3.0V$)

6.4.8. Output voltage vs. input voltage ($V_{out} = 2.55V$)


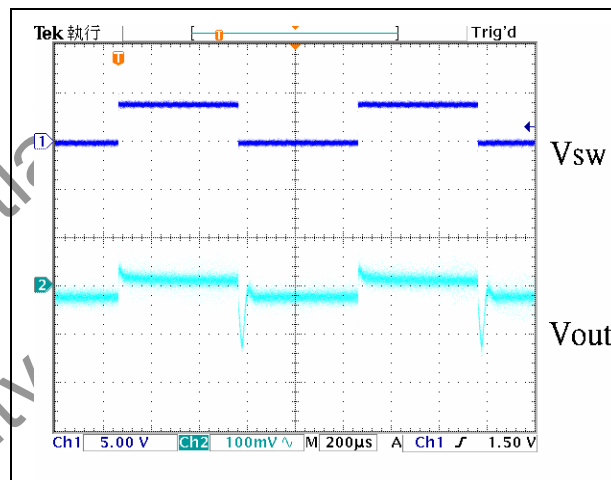
6.4.9. Output voltage vs. temperature (Vout = 3.3V)

6.4.11. Output voltage vs. temperature (Vout = 2.7V)

6.4.10. Output voltage vs. temperature (Vout = 3.0V)

6.4.12. Output voltage vs. Temperature (Vout = 2.55V)


6.4.13. Load –transient response test module

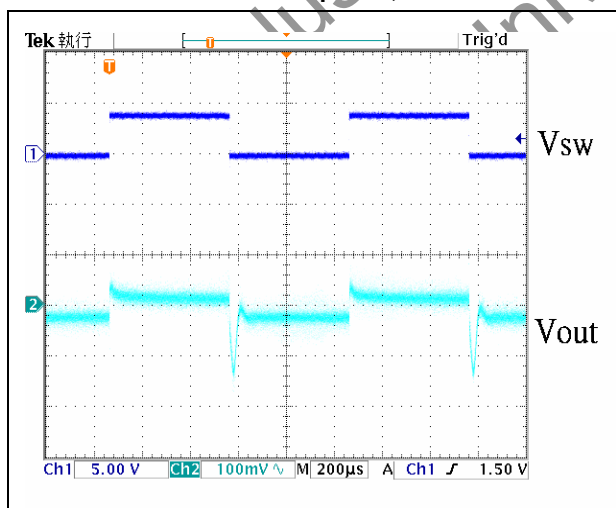
($V_{IN} = 5V$, $I_{OUT} = 0$ to $50mA$, $C_{LOAD} = 10\mu F$)



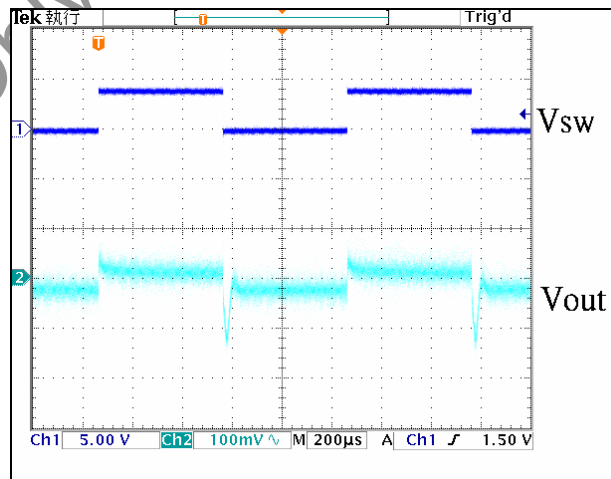
6.4.16. Load –transient response; $V_{out} = 2.7V$



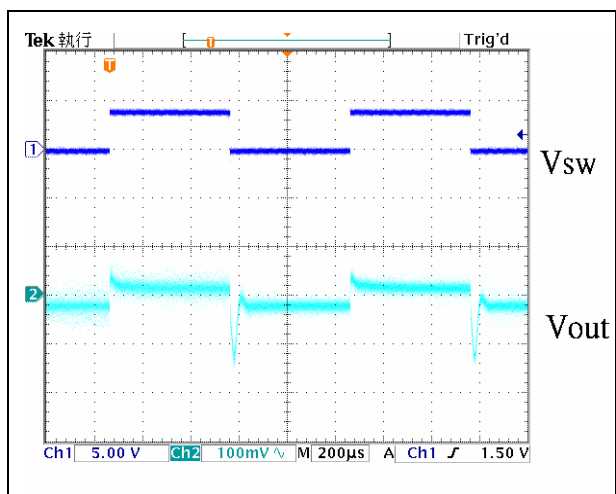
6.4.14. Load –transient response; $V_{out} = 3.3V$



6.4.17. Load –transient response; $V_{out} = 2.55V$

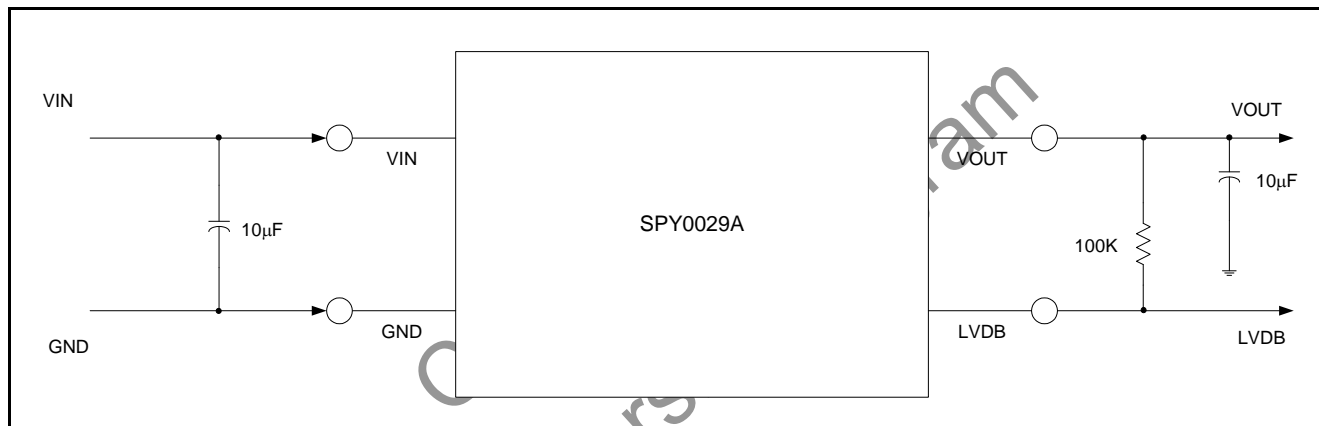


6.4.15. Load –transient response; $V_{out} = 3.0V$

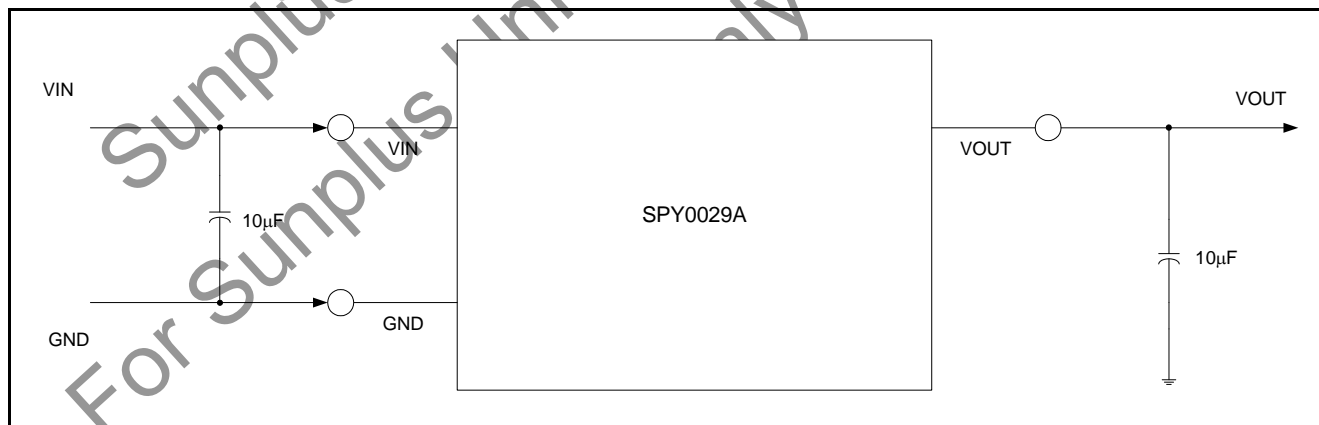


6. APPLICATION CIRCUIT

6.1. 4 PIN (with Low Voltage Detected Function)



6.2. 3 PIN (no Low Voltage Detected Function)



7. PACKAGE/PAD LOCATIONS**7.1. PAD Assignment and Locations**

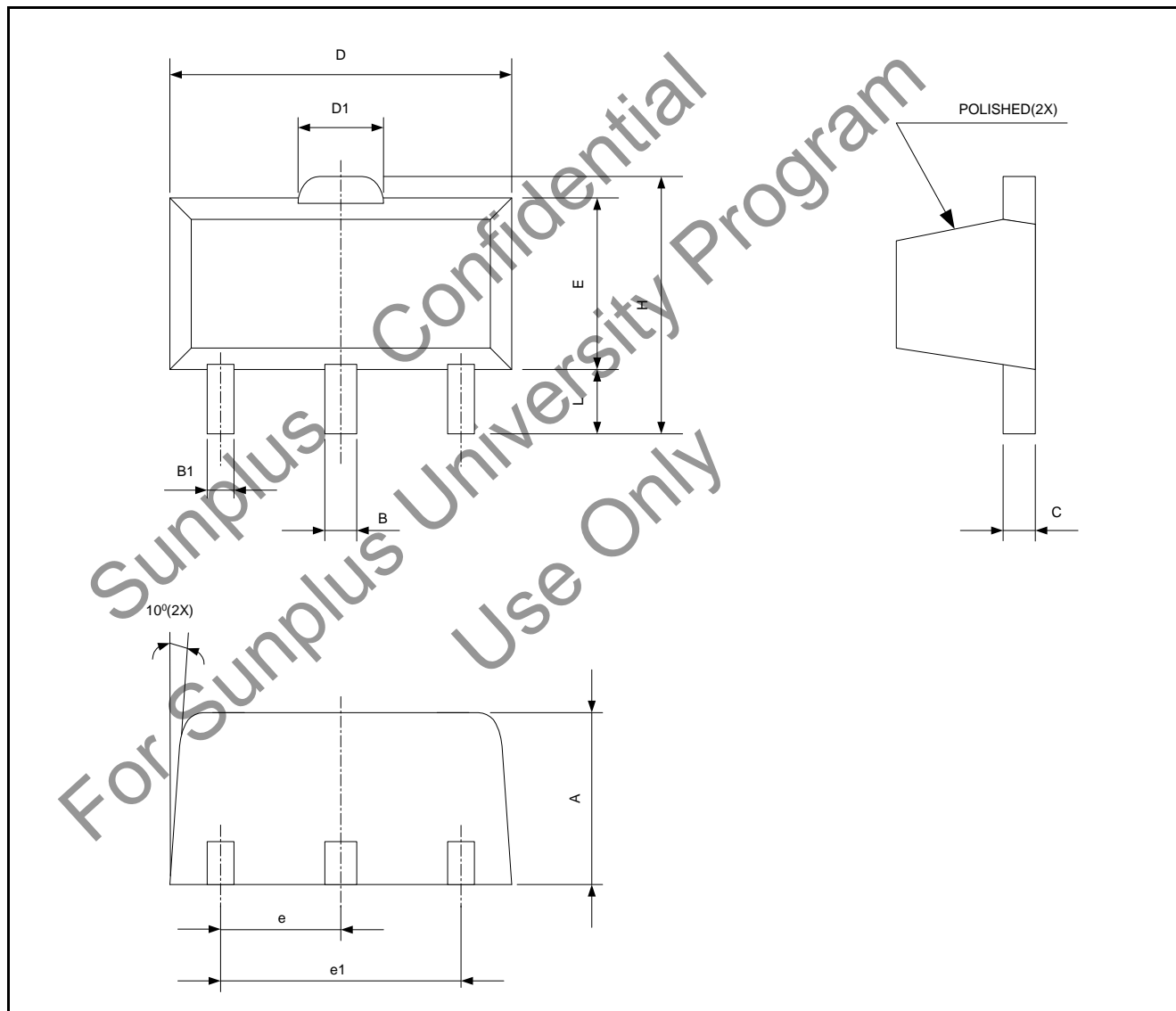
Please contact Sunplus sales representatives for more information.

7.2. Ordering Information

| Product Number | Package Type |
|----------------|-------------------------------------|
| SPY0029A-C | Chip form |
| SPY0029A-RE011 | Package form - SOT89 (Vout = 3.3V) |
| SPY0029A-RE012 | Package form - SOT89 (Vout = 3.0V) |
| SPY0029A-RE013 | Package form - SOT89 (Vout = 2.7V) |
| SPY0029A-RE014 | Package form - SOT89 (Vout = 2.55V) |

7.3. Package Information

7.3.1. 3 PIN SOT89 package size



| Symbol | Min. | Max. | Unit |
|--------|----------|------|------------|
| A | 1.40 | 1.60 | Millimeter |
| B | 0.44 | 0.56 | Millimeter |
| B1 | 0.36 | 0.48 | Millimeter |
| C | 0.35 | 0.44 | Millimeter |
| D | 4.40 | 4.60 | Millimeter |
| D1 | 1.35 | 1.83 | Millimeter |
| E | 2.29 | 2.60 | Millimeter |
| H | 3.94 | 4.25 | Millimeter |
| e | 1.50 BSC | | Millimeter |
| e1 | 3.00 BSC | | Millimeter |
| L | 0.89 | 1.2 | Millimeter |

7.4. Storage Condition and Period for Package

| Package | Moisture sensitivity level | Max. Reflow temperature | Floor life storage condition | Dry pack |
|---------|----------------------------|-------------------------|------------------------------|----------|
| SOT | LEVEL 3 | 220 +5/-0°C | N/A | No |

Note1: Please refer to IPC/JEDEC standard J-STD-020A and EIA JEDEC stand JFSD22-A112

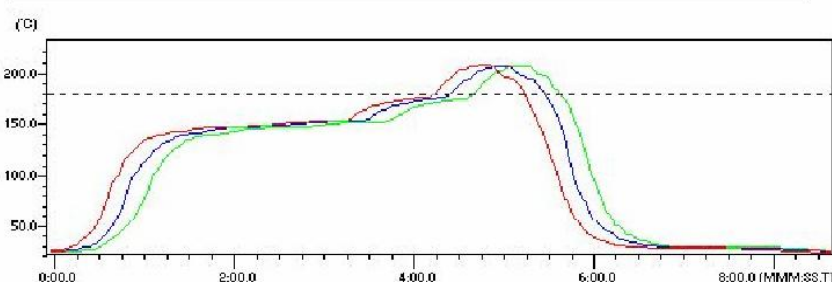
Note2: or refer to the "CAUTION Note" on dry pack bag.

7.5. Recommended SMT Temperature Profile

This "Recommended" temperature profile is a rough guideline for SMT process reference. Most of SUNPLUS leadframe base product choice Matte Tin and Sn/Bi for plating recipe. For

PPF(Pre-Plated Frame) product with 63/37 solder paste, we recommend 240°C~245°C for peak temperature.

Recommended Reflow Profile for 63/37 Solder Paste or Cu lead frame

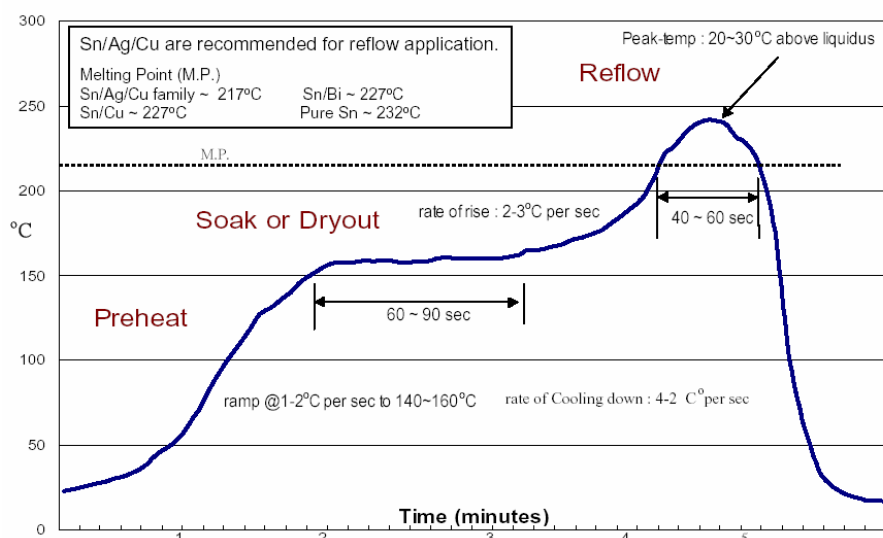


This profile is designed for use with Sn63 or Sn62 and can serve as a general guideline in establishing a reflow profile.

Reflow Profile:

- Heating-up @1~3°C per sec to 140°C
- Preheat @ 140-150°C for 120 ~ 160 sec
- Ramp @ 2~3 °C per sec to peak temperature (220 ~ 225 °C), Temperature over 183°C for 45~ 75 sec
- Cooling down to room temperature @4~2°C per sec to avoid undesired intermetallic compound layer.

Recommended Reflow Profile for Lead-free Solder Paste or PPF lead frame



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9. REVISION HISTORY

| Date | Revision # | Description | Page |
|---------------|------------|----------------------------------------------------------------------------------------|------|
| APR. 15, 2005 | 0.6 | 1. Update absolute maximum ratings | 5 |
| | | 2. Add section 7.4 Storage Condition and Period for Package | 14 |
| | | 3. Add section 7.5 Recommended SMT Temperature Profile | 14 |
| DEC. 20, 2004 | 0.5 | 1.Update Ordering Information | 4 |
| FEB. 25, 2004 | 0.4 | 1.Remote 4pin package type TO-92 , add into 4pin COB type | 4 |
| | | 2.Update Ordering Information | 5 |
| | | 3.Update output voltage accuracy=+/-10% | 6 |
| | | 4.Update output current=100mA (Typ) | 6 |
| | | 5. Remove " <u>8.1 PAD Assignment and Locations</u> " | 12 |
| JAN.28, 2003 | 0.3 | Update Ordering Information SPY0029A-RE011, SPY0029A-RE013 and SPY0029A-RE014 | 11 |
| OCT.15, 2002 | 0.2 | 1. Update quiescent current = 3.0μA in Features | 3 |
| | | 2. Update quiescent current = 3.0μA in DC characteristic | 5 |
| | | 3. Add $V_{OUT} = 3.3V$ into test conditions of DC characteristic | 5 |
| | | 4. Add Note1 figure into bonding option | 5 |
| | | 5. Add typical operating characteristic figures from page 6 to page 9 (6.4.1 ~ 6.4.17) | 6 |
| JUL. 10, 2002 | 0.1 | Original | 12 |